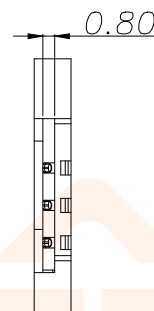
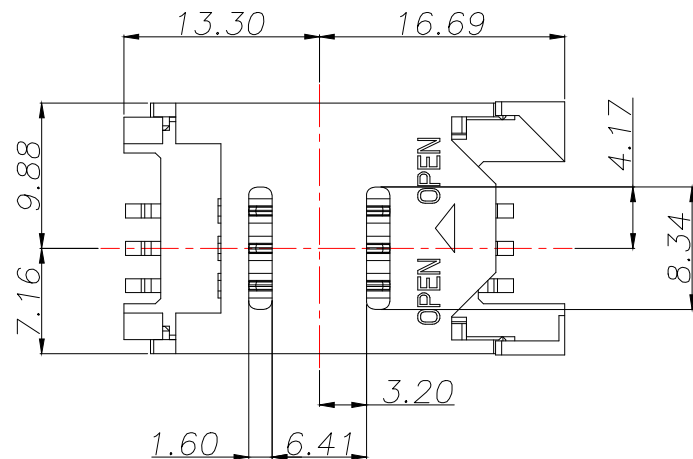


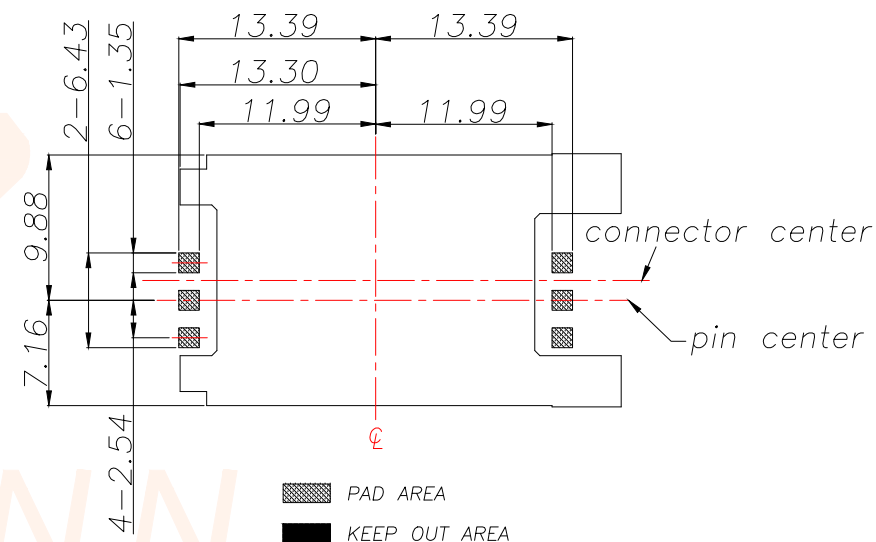
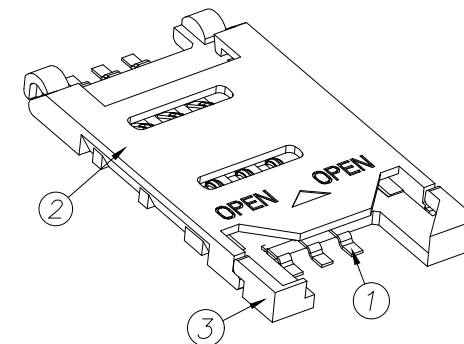


REV.	ECN NO.	DESCRIPTION	DATE	DESIGN

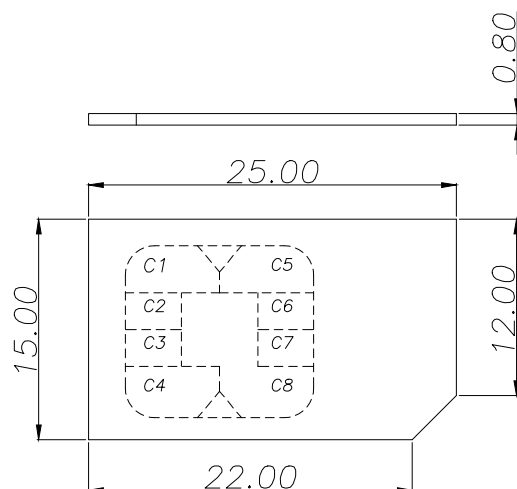


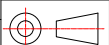
MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

1)MATERIAL:
HOUSING: THERMOPLASTIC,UL 94V-0,
COLOR:BLACK
CONTACT: COPPER ALLOY
2)FINISH
CONTACT: GOLD FLASH
SOLDER AREA: TIN 100u" Min
3)Solder-ability
IR reflow:250°C,5sec.Max
Manual soldering:350°C ,3sec.max



■ PAD AREA
■ KEEP OUT AREA
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



1	Contact	COPPER ALLOY	Gold FLASH	6	
2	Cover	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
3	Housing	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
ITEM	NAME	MATERIAl	FINISH	Q'ty	REMARK
TOLERANCE		 深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd			
X.±0.50	X.*±2°	PART NO. MINI SIM-011B-P6	TITLE: SIM CARD CONN 插盖式 H2.5mm		
X.X±0.30	X.X*±1°				
X.XX±0.20					
UNITS	mm	DESIGN: Ethan	MANUFACTURE DWG		
MATERILA	— — —	CHED: Olvia			
FINISH	— — —	APPD: Ava			
				SCALE N:A	SHEET 1/2

